PDS BOM-PMP9559REVB.xls
None
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N/A

PMP9559 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C8, C12, C17, C18, C19, C24	7	0.1uF	C1005X7R1H104K	TDK	CAP, CERM, 0.1 µF, 50 V, +/- 10%, C0G/NP0, 0402	0402
C2, C3	2	22uF	GRM31CR61C226KE15L	MuRata	CAP, CERM, 22 µF, 16 V, +/- 10%, X5R, 1206	1206
C4, C5	2	0.01uF	C1005X7R1C103K	TDK	CAP, CERM, 0.01 µF, 16 V, +/- 10%, X7R, 0402	0402
C6, C11, C26, C27	4	1000pF	C1005C0G1E102J	TDK	CAP, CERM, 1000 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
C7, C15	2	2200pF	C1005X7R1H222K	TDK	CAP, CERM, 2200 pF, 50 V, +/- 10%, X7R, 0402	0402
C9, C13	2	47pF	GRM1555C1E470JA01D	MuRata	CAP, CERM, 47 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
C10, C14, C21, C23	4	47uF	C3216X5R1C476M160AB	TDK	CAP, CERM, 47 µF, 16 V, +/- 15%, X5R, 1206	1206
C20	1	10uF	C1608X5R1A106M	TDK	CAP, CERM, 10 µF, 10 V, +/- 20%, X5R, 0603	0603
C22	1	1uF	C1608X7R1C105K	TDK	CAP, CERM, 1 µF, 16 V, +/- 10%, X7R, 0603	0603
J1, J2	2		U.FL-R-SMT-1	Hirose Electric Co. Ltd.	Connector, Ultra-Mini Coaxial, SMD	Ultra small CO-AX SMD
L1, L2	2	2.2uH	XAL5030-222MEB	Coilcraft	Inductor, Shielded, Composite, 2.2 µH, 9.2 A, 0.01 ohm, SMD	5.3x31.x5.5mm
Q1, Q2	2		CSD87381P	Texas Instruments	Synchronous Buck NexFET Power Block II, MPC0005A	MPC0005A
Q3, Q4	2	40 V	MMBT3904T-7-F	Diodes Inc.	Transistor, NPN, 40 V, 0.2 A, SOT-523	SOT-523
R1, R12	2	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0, 1%, 0.063 W, 0402	0402
R2, R14	2	200	CRCW0402200RFKED	Vishay-Dale	RES, 200, 1%, 0.063 W, 0402	0402
R3, R30	2	2.49k	CRCW04022K49FKED	Vishay-Dale	RES, 2.49 k, 1%, 0.063 W, 0402	0402
R4, R7, R23, R29	4	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
R5, R16	2	10.0k	PCF0402-12-10KBT1	TT Electronics/IRC	RES, 10.0 k, 0.1%, 0.063 W, 0402	0402
R6, R8, R20, R33	4	4.99k	CRCW04024K99FKED	Vishay-Dale	RES, 4.99 k, 1%, 0.063 W, 0402	0402
R9, R32	2	5.1	CRCW04025R10JNED	Vishay-Dale	RES, 5.1, 5%, 0.063 W, 0402	0402
R10, R18	2	1.37k	CRCW04021K37FKED	Vishay-Dale	RES, 1.37 k, 1%, 0.063 W, 0402	0402
R11, R19	2	294k	CRCW0402294KFKED	Vishay-Dale	RES, 294 k, 1%, 0.063 W, 0402	0402
R17, R35	2	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402	0402
R27, R28	2	38.3k	CRCW040238K3FKED	Vishay-Dale	RES, 38.3 k, 1%, 0.063 W, 0402	0402
R31	1	66.5k	CRCW040266K5FKED	Vishay-Dale	RES, 66.5 k, 1%, 0.063 W, 0402	0402
R34	1	1.0	CRCW04021R00JNED	Vishay-Dale	RES, 1.0, 5%, 0.063 W, 0402	0402
U1	1	TPS40422RHA	TPS40422RHA	TI	IC, PMBUS synchronous buck controller	QFN-40

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